Technical Data *Green Products*
Data Sheet N0526, Rev. -

1N914 /DL914 FAST SWITCHING DIODE

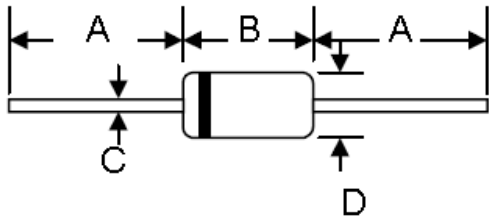
Features:

- **Fast Switching Speed**
- **Glass Package Version for High Reliability**
- **High Conductance**
- **Available in Both Through-Hole and Surface Mount Versions**
- **This is a Pb − Free Device**
- **All SMC parts are traceable to the wafer lot**
- **Additional testing can be offered upon request**

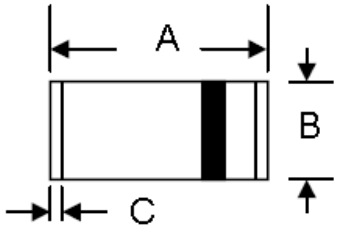
Mechanical Data:

- **Case: DO-35, DL-35**
- **Terminals: Plated leads Solderable per MIL-STD-202, Method 208**
- **Polarity: Cathode Band**
- **Weight: DO-35 0.13 grams**
  DL-35 0.05 grams
- **Marking: Part Name, SSG and Marking code for date code**

Mechanical Dimensions: In mm/Inches



1N914



DL914

DO-35				
Dim	Min	Max	Min	Max
A	25.40	—	1.000	—
B	—	4.00	—	0.157
C	—	0.60	—	0.024
D	—	2.00	—	0.079
	in mm		In inch	

MiniMELF				
Dim	Min	Max	Min	Max
A	3.30	3.70	0.130	0.146
B	1.30	1.60	0.051	0.063
C	0.28	0.50	0.011	0.020
	In mm		In inch	

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Maximum Ratings @T_A=25°C unless otherwise specified

Characteristic	Symbol	Limits	Unit
Non- Repetitive Peak Reverse Voltage	V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	75	V
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Forward Current	I_F	300	mA
Rectified Current(Average), Half Wave Rectification with Resistive Load and f≥50MHz (Note 1)	I_O	150	mA
Non-Repetitive Peak Forward Surge Current @t=1.0s @t=1.0μs	I_{FSM}	1.0 2.0	A
Power Dissipation Derate Above 25°C	P_D	500 1.68	mW mW/°C
Typical Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	300	°C/W
Junction and Storage Temperature Range	T_J, T_{STG}	-65 to +175	°C

Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Forward Voltage	V_{FM}	-	1.0	V	@I_F=10mA
Reverse Leakage Current	I_{RM}	-	5.0 50 30 25	uA uA uA nA	@V_R=75V @V_R=70V, T_J=150°C @V_R=20V, T_J=150°C @V_R=20V
Capacitance	C_T	-	4	pF	V_R=0V, f=1.0MHz
Reverse Recovery Time	t_{rr}	-	4	ns	I_F=10mA to I_R=1.0mA, V_R=6V, R_L=100Ω

Note: 1. Diode on Substrate substrate 10×8×0.7mm

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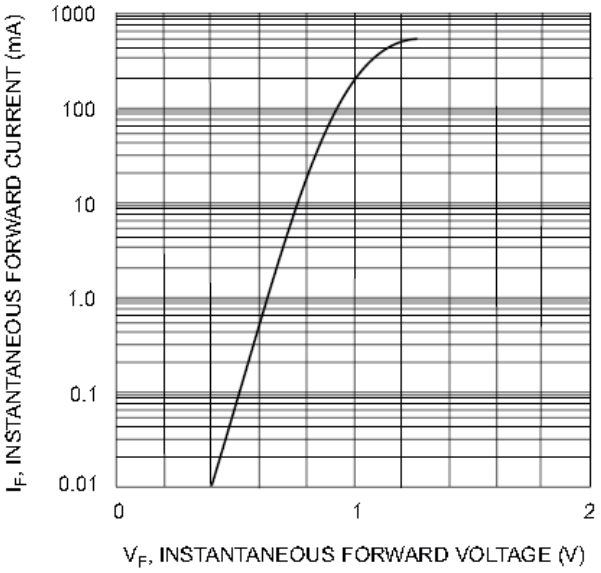


Fig. 1 Forward Characteristics

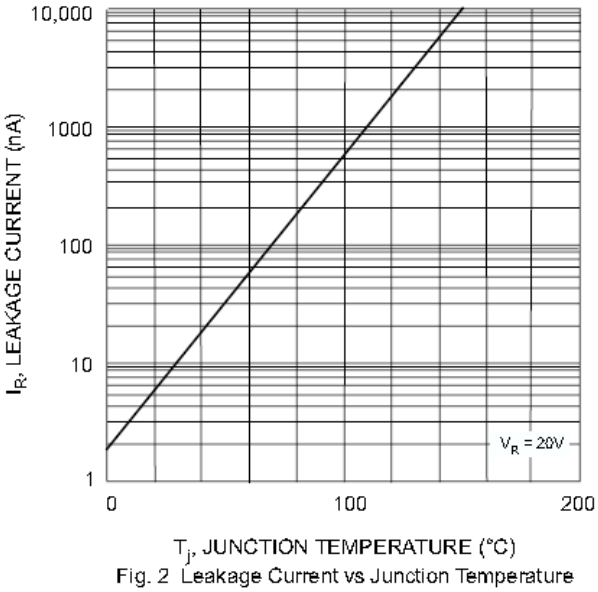


Fig. 2 Leakage Current vs Junction Temperature

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